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09/434,507	11/05/1999	CHARLES J. STOUFFER	2288-006	4043
26171	7590	07/11/2005	EXAMINER	
FISH & RICHARDSON P.C. P.O. BOX 1022 MINNEAPOLIS, MN 55440-1022			NEWHOUSE, NATHAN JEFFREY	
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Please find below and/or attached an Office communication concerning this application or proceeding.

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This is in response to the Remand to the Examiner on 10/23/03 for further clarification with respect to consideration of a rejection under 102/103 with Stouffer et al. (US 6264095) alone or in combination with other prior art. See Remand footnote #7 on page 5 and continuing to page 6.

If it is found that the Gieser reference does not anticipate or obviate the claims as set forth in the examiner's answer, then it would appear to be appropriate to make a rejection under 35 USC 103 of Gieser (US 2941064) in view of Stouffer et al. (US 6264095) wherein Gieser teaches everything except it is unclear if the welding to join sides 17 and 18 of outer shell 7 and bottom end wall 12 is "diffusion bonding". Stouffer et al. teaches that "diffusion bonding" or a hot isostatic pressure (HIP) bond method is used to join two metal blanks. While Stouffer et al. teaches that these metal blanks and HIP bond method works well for beryllium, the parameters are varied to suit the properties of the chosen material. (see col. 3 lines 39-51, especially lines 46-51). Therefore it would be obvious to one of ordinary skill in the art at the time of the invention to use the HIP bond method or diffusion bonding to join the sides of the outer shell and bottom end wall of Gieser as a mere substitution of known methods for joining materials. Moreover, the HIP bond method or diffusion bond provides a more reliable attachment.



NATHAN J. NEWHOUSE  
PRIMARY EXAMINER

7/7/05